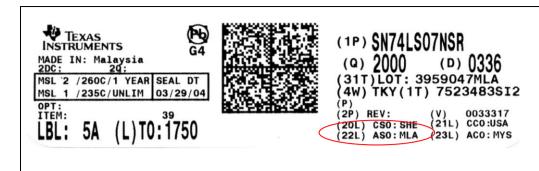
PCN Num	ber:	201	/122	200	100B					P	CN Date:	Feb. 1 2018	
Title:	Title: Assembly site (AP3) transfer for select Devices												
Customer PCN Mai		Manag	ger		D	ept:	Quality Services						
Proposed Date:	1 st Ship		Ма	Mar 21 2018			Estima	ted Sample Availability: Provided under the Request			Provided upon Request		
Change T	ype:												
	embly Site				Assembl	ly F	Process Assembly			Materials			
Desi	ign						pecificati	on			Mechanical Specification		
	Site						ipping/La				Test Proc	ess	
Wafe	er Bump Si	ite					p Materia				Wafer Bump Process		
	er Fab Site						Materials				Wafer Fab Process		
			Ī		Part nur	nbe	er change				1		
							CN Deta						
Description	on of Cha	nge:											
notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only. Texas Instruments is pleased to announce the qualification of subcontractor Amkor P3 as a new Assembly site for the list of devices shown below. There are no material construction differences between the 2 sites.													
Reason for Change:													
Continuity	of Supply												
Anticipat	ed impact	on Fi	it, Fo	orr	n, Functi	ion	, Quality	or Reliabili	ity	/ (p	ositive / n	egative):	
None													
Anticipated impact on Material Declaration													
the	No Impact to the Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.						oduction release.						
Changes	Changes to product identification resulting from this PCN:												

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
Amkor K4	AMP	KOR	Gwangju
Amkor P3	AP3	PHL	Binan

Sample product shipping label (not actual product label)



Product Affected								
	AFE8406IZDQ	MM9618-UCB/S7001631	TNETV1051EACLZDW	TNETV1052ACLZDW				
	DAC5670IGDJ	SM320F28335GJZMEP	TNETV1051INZDW	TNETV1053ZDW				
	GC5018IZDL	TNETV1051DACLZDW	TNETV1051ZDW	V62/09624-01XE				



TI Information Selective Disclosure

Qualification Report

Transfer of assembly of K4 PBGA products

Approve Date 13-Nov-2017

Product Attributes

Package Attributes	Qual Device: MM9760UFG-SCD/S1	Qual Device: TLK4015IZPV	Qual Device: TMS320C6211BGFN150	Qual Device: TNETV1051EACLZDW	Qual Device: TNETV2021AZDS
Assembly Site	AP3	AP3	AP3	AP3	AP3
Package Family	BGA	BGA	PBGA	PBGA	PBGA
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MFAB	ANAM-1	DP1DM5	DMOS6	DP1DM5
Wafer Process	CMOS7	C10	1833C07	1533C035.1	1533C05.A

- QBS: Qual By Similarity
- Qual Device MM9760UFG-SCD/S1 is qualified at LEVEL4-220C
- Qual Device TLK4015IZPV is qualified at LEVEL3-260C
- Qual Device TMS320C6211BGFN150 is qualified at LEVEL4-220C
- Qual Device TNETV1051EACLZDW is qualified at LEVEL4-260C
- Qual Device TNETV2021AZDS is qualified at LEVEL3-260C
- Device TLK4015IZPV contains multiple dies.

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: MM9760UFG- SCD/S1	Qual Device: TLK4015IZPV	Qual Device: TMS320C6211BG FN150	Qual Device: TNETV1051EACLZ DW	Qual Device: TNETV2021AZDS
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0	-	-	-
MQ	Manufacturability	(per mfg. site specification)	3/Pass	3/Pass	3/Pass	3/Pass	3/Pass
MSL	Moisture Sensitivity	Level 3-260C	-	3/36/0	-	-	3/36/0
MSL	Moisture Sensitivity	Level 4-220C	3/36/0	-	3/36/0	-	-
MSL	Moisture Sensitivity	Level 4-260C	-	-	-	3/36/0	-
PKG	Warpage (Shadow Moiré)	-	Pass	Pass	-	-	Pass
тс	Temperature Cycle, - 55/125C	1000 Cycles	3/231/0	3/231/0	3/231/0	-	3/231/0
TC- SAM	Post Temp Cycle SAM	700 Cycles	3/36/0	3/36/0	3/36/0	-	3/36/0
UHAS T	Unbiased HAST, 110C/85%RH	264 Hours	3/231/0	3/231/0	-	-	3/231/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass	3/Pass	3/Pass	3/Pass

⁻ Preconditioning was performed for Unbiased HAST, Temperature Cycle, and HTSL, as applicable.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
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Japan	PCNJapanContact@list.ti.com

⁻ The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours.

⁻ The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles.